



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2015-11-22</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Floriana San Biagio</b>	<b>Representative Title</b>	<b>AMS Materials Declaration Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STA369BWS	B2EH*UA92AA5	A	MU1A	2015-11-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	480.00	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	10.30x7.5x2.28	36	gull wing	
Comment	Package: EH PowerSSO36; MDF valid also for STA369BWSTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	B2EH*UA92AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	11.049	mg	supplier	die	Silicon (Si)	7440-21-3		10.455	mg	946239	21781
				supplier	metallization	Aluminium (Al)	7429-90-5		0.080	mg	7240	167
				supplier	metallization	Tungsten (W)	7440-33-7		0.064	mg	5792	133
				supplier	Passivation	Silicon Nitride	12033-89-5		0.017	mg	1539	35
				supplier	Passivation	Silicon Oxide	7631-86-9		0.137	mg	12399	285
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.006	mg	543	13
				supplier	back side metallization	Gold (Au)	7440-57-5		0.016	mg	1448	33
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.053	mg	4797	110
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.137	mg	12399	285
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.084	mg	7602	175
Leadframe	Copper & its alloys	133.366	mg	supplier	alloy	Copper (Cu)	7440-50-8		128.102	mg	960530	266879
				supplier	alloy	Iron (Fe)	7439-89-6		3.013	mg	22592	6277
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.181	mg	1357	377
				supplier	alloy	Zinc (Zn)	7440-66-6		0.158	mg	1185	329
				supplier	metallization	Silver (Ag)	7440-22-4		1.912	mg	14336	3983
Soft solder	Other inorganic materials	6.748	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high melting	6.580	mg	975104	13708
				supplier	solder	Silver (Ag)	7440-22-4		0.101	mg	14967	210
				supplier	solder	Tin (Sn)	7440-31-5		0.067	mg	9929	140
Bonding wires	Other inorganic materials	0.995	mg	supplier	wire	Copper (Cu)	7440-50-8		0.995	mg	1000000	2073
Encapsulation	Other Organic Materials	323.609	mg	supplier	mold compound	silica vitreous	60676-86-0		286.395	mg	885003	596656
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		17.151	mg	52999	35731
				supplier	mold compound	Phenol Resin	205830-20-2		12.944	mg	39999	26967
				supplier	mold compound	epoxy resin	Proprietary		6.472	mg	19999	13483
				supplier	mold compound	carbon black	1333-86-4		0.647	mg	1999	1348
connections coating	Finishing	4.233	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.233	mg	1000000	8819